OptiMOS®3 Power-Transistors

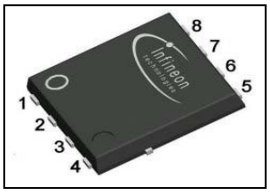
Features

- Dual N-channel, logic level
- Fast switching MOSFETs for SMPS
- Optimized technology for DC/DC converters
- Qualified according to JEDEC[1] for target applications
- Excellent gate charge x $R_{DS(on)}$ product (FOM)
- Very low on-resistance $R_{DS(on)}$
- Superior thermal resistance
- 100% Avalanche tested
- Pb-free plating; RoHS compliant

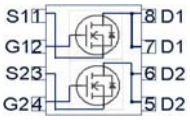
Product Summary

V_{DS}	30	V
$R_{DS(on),max}$	15	mΩ
I_D	20	A

PG-TDSON-8



Type	Package	Marking
BSC150N03LD G	PG-TDSON-8	150N03LD



Maximum ratings, at T_j=25 °C, unless otherwise specified

Parameter	Symbol	Conditions	Value		Unit
			≤10 secs	steady state	
Continuous drain current	I_D	V_{GS}=10 V, T_C=25 °C	20		A
		V_{GS}=10 V, T_C=100 °C	20		
		V_{GS}=4.5 V, T_C=25 °C	20		
		V_{GS}=4.5 V, T_C=100 °C	17		
		V_{GS}=10 V, T_A=25 °C[3]	12.4	8	
Pulsed drain current[2]	$I_{D,pulse}$	T_C=25 °C	80		
Avalanche energy, single pulse	E_{AS}	I_D=20 A, R_{GS}=25 Ω	10		mJ
Gate source voltage	V_{GS}		±20		V
Power dissipation	P_{tot}	T_C=25 °C	26		W
		T_A=25 °C[3]	3.6	1.5	
Operating and storage temperature	T_j, T_{stg}		-55 ... 150		°C
IEC climatic category; DIN IEC 68-1			55/150/56		

[1] J-STD20 and JESD22

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Thermal characteristics						
Thermal resistance, junction - case	R_{thJC}		-	-	4.9	K/W
Thermal resistance, junction - ambient, 6 cm² cooling area[3)]	R_{thJA}	t≤10 s	-	-	35	
		steady state	-	-	85	
Electrical characteristics, at T_j=25 °C, unless otherwise specified						
Static characteristics						
Drain-source breakdown voltage	$V_{(BR)DSS}$	V_{GS}=0 V, I_D=1 mA	30	-	-	V
Gate threshold voltage	$V_{GS(th)}$	V_{DS}=V_{GS}, I_D=250 µA	1	-	2.2	
Zero gate voltage drain current	I_{DSS}	V_{DS}=30 V, V_{GS}=0 V, T_j=25 °C	-	0.1	1	µA
		V_{DS}=30 V, V_{GS}=0 V, T_j=125 °C	-	10	100	
Gate-source leakage current	I_{GSS}	V_{GS}=20 V, V_{DS}=0 V	-	10	100	nA
Drain-source on-state resistance	$R_{DS(on)}$	V_{GS}=4.5 V, I_D=20 A	-	17.6	22	mΩ
		V_{GS}=10 V, I_D=20 A	-	12.5	15	
Gate resistance	R_G		-	1.2	1.8	Ω
Transconductance	g_{fs}	$\|V_{DS}\|>2\|I_D\|R_{DS(on)max}$, I_D=20 A	18	35	-	S

[2)] See figure 3

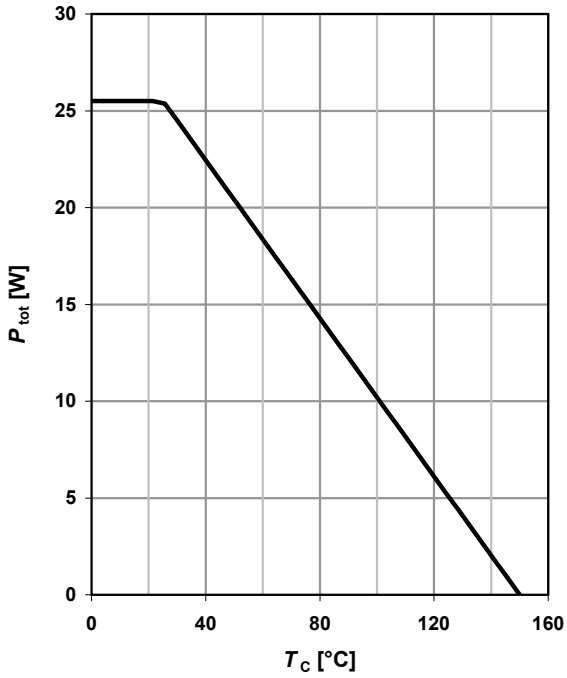
[3)] Device on 40 mm x 40 mm x 1.5 mm epoxy PCB FR4 with 6 cm² (one layer, 70 µm thick) copper area for drain connection. PCB is vertical in still air. One transistor active.

Parameter	Symbol	Conditions	Values			Unit
			min.	typ.	max.	
Dynamic characteristics						
Input capacitance	C_{iss}	V_{GS}=0 V, V_{DS}=15 V, f=1 MHz	-	850	1100	pF
Output capacitance	C_{oss}		-	350	470	
Reverse transfer capacitance	C_{rss}		-	16	-	
Turn-on delay time	$t_{d(on)}$	V_{DD}=15 V, V_{GS}=10 V, I_D=20 A, R_G=1.6 Ω	-	2.7	-	ns
Rise time	t_r		-	2.2	-	
Turn-off delay time	$t_{d(off)}$		-	12	-	
Fall time	t_f		-	2.0	-	
Gate Charge Characteristics[4)]						
Gate to source charge	Q_{gs}	V_{DD}=15 V, I_D=20 A, V_{GS}=0 to 4.5 V	-	2.6	-	nC
Gate charge at threshold	$Q_{g(th)}$		-	1.2	-	
Gate to drain charge	Q_{gd}		-	1.2	-	
Switching charge	Q_{sw}		-	2.6	-	
Gate charge total	Q_g		-	4.8	6.4	
Gate plateau voltage	$V_{plateau}$		-	3.4	-	V
Gate charge total	Q_g	V_{DD}=15 V, I_D=20 A, V_{GS}=0 to 10 V	-	10	13.2	nC
Gate charge total, sync. FET	$Q_{g(sync)}$	V_{DS}=0.1 V, V_{GS}=0 to 4.5 V	-	4.2	-	
Output charge	Q_{oss}	V_{DD}=15 V, V_{GS}=0 V	-	9	-	
Reverse Diode						
Diode continuous forward current	I_S	T_C=25 °C	-	-	20	A
Diode pulse current	$I_{S,pulse}$		-	-	80	
Diode forward voltage	V_{SD}	V_{GS}=0 V, I_F=20 A, T_j=25 °C	-	0.93	1.1	V
Reverse recovery charge	Q_{rr}	V_R=15 V, I_F=I_S, di_F/dt=400 A/µs	-	-	10	nC

[4)] See figure 16 for gate charge parameter definition

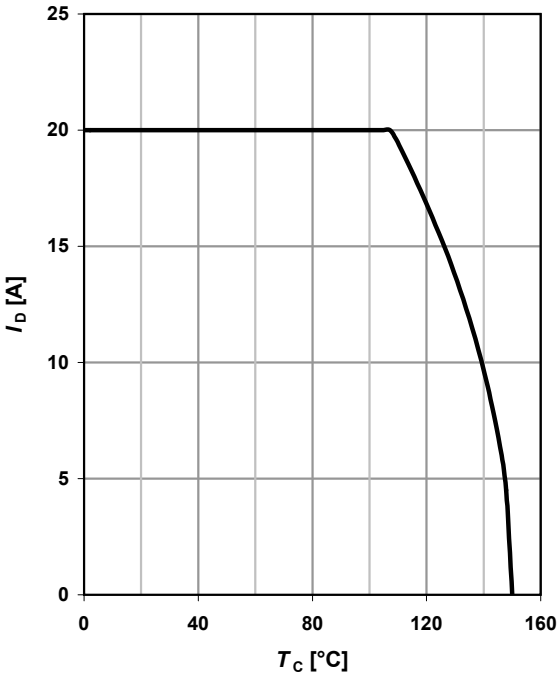
1 Power dissipation

$P_{tot}=f(T_C)$



2 Drain current

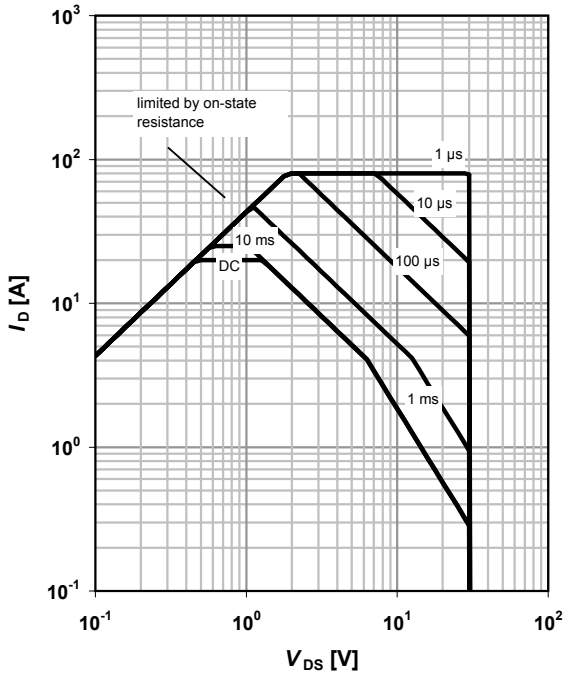
$I_D=f(T_C)$; $V_{GS}\geq 10$ V



3 Safe operating area

$I_D=f(V_{DS})$; $T_C=25$ °C; $D=0$

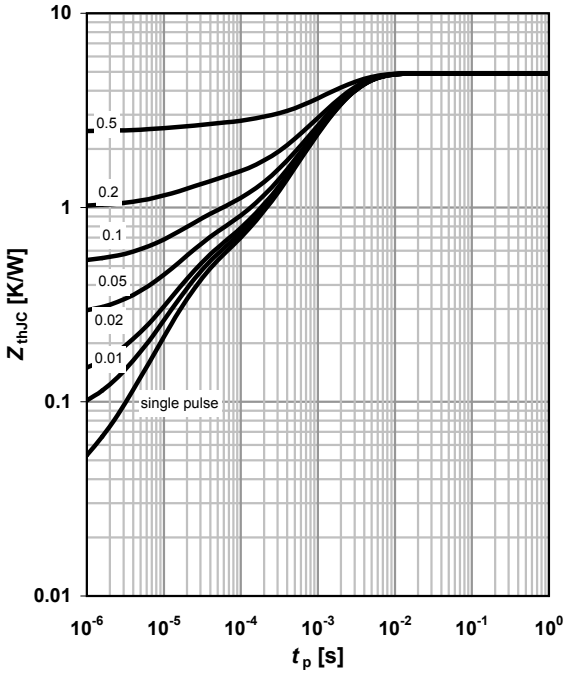
parameter: t_p



4 Max. transient thermal impedance

$Z_{thJC}=f(t_p)$

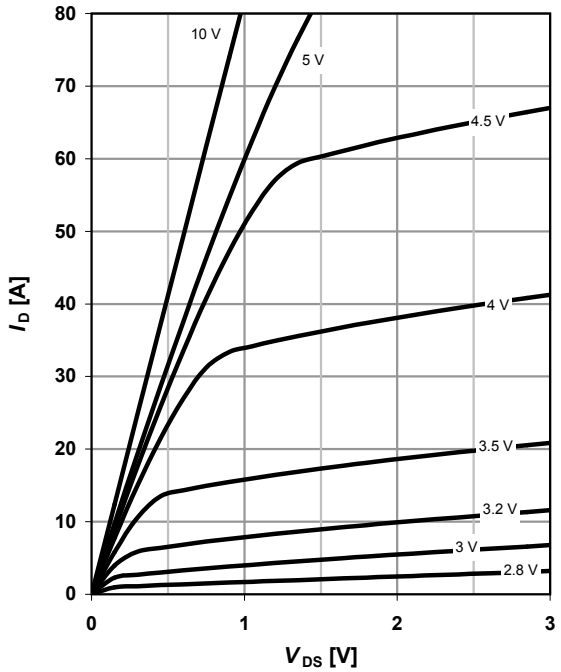
parameter: $D=t_p/T$



5 Typ. output characteristics

I_D=f(V_{DS}); T_j=25 °C

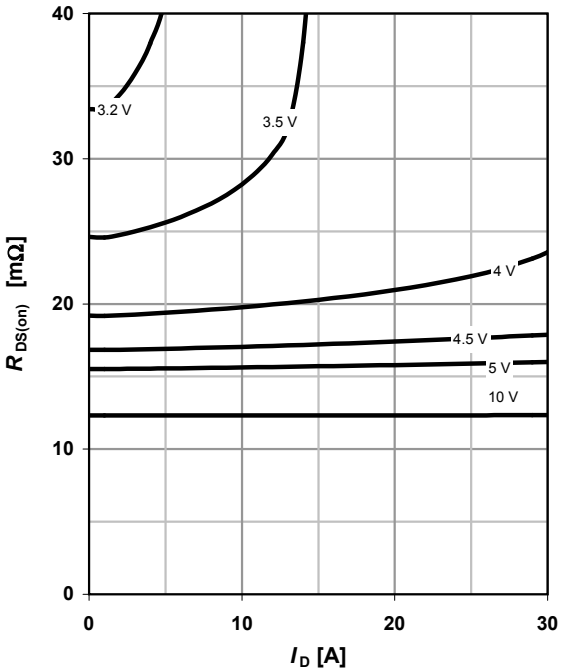
parameter: V_{GS}



6 Typ. drain-source on resistance

$R_{DS(on)}$=f(I_D); T_j=25 °C

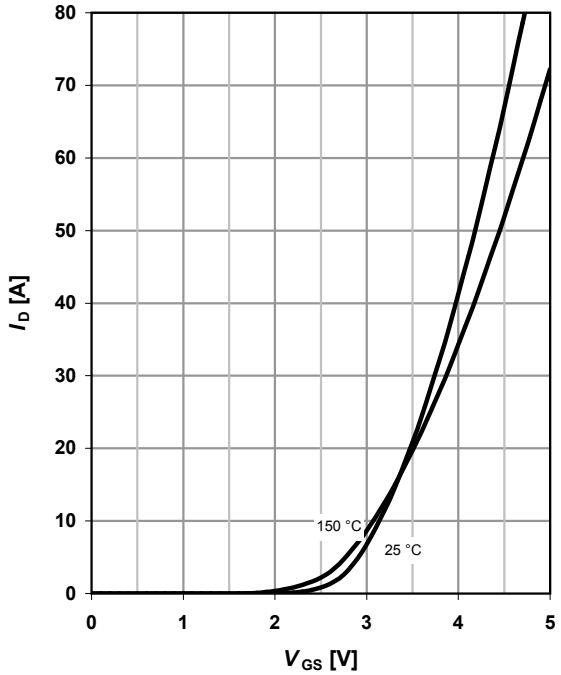
parameter: V_{GS}



7 Typ. transfer characteristics

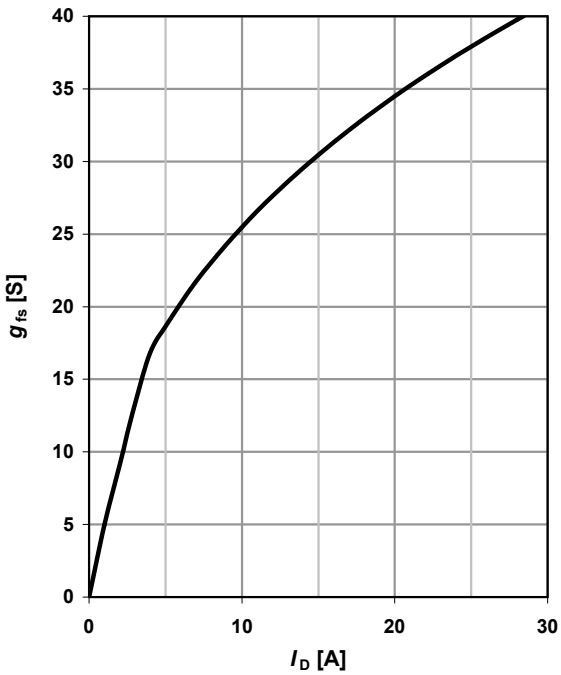
I_D=f(V_{GS}); $|V_{DS}|>2|I_D|R_{DS(on)max}$

parameter: T_j



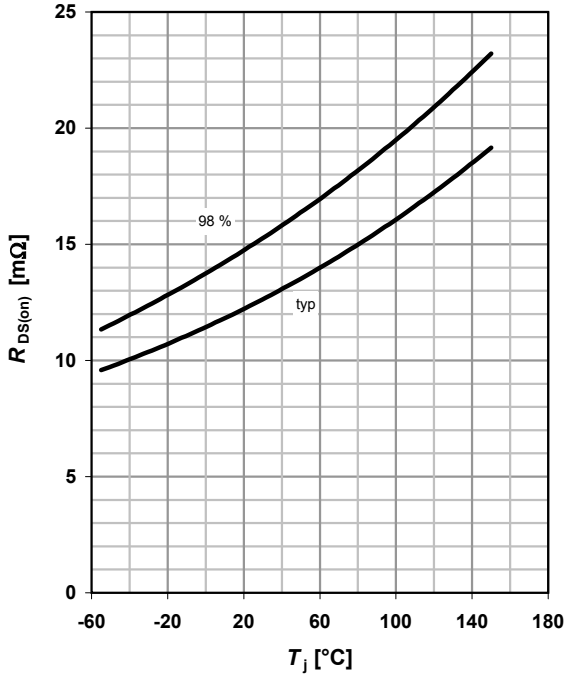
8 Typ. forward transconductance

g_{fs}=f(I_D); T_j=25 °C



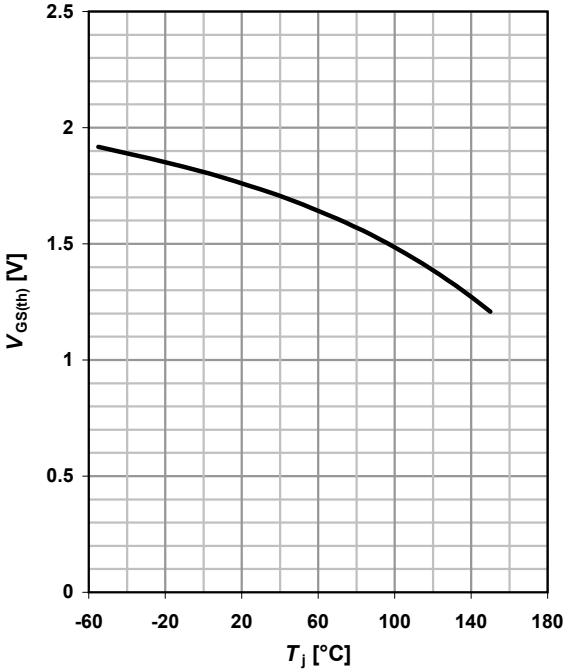
9 Drain-source on-state resistance

$R_{DS(on)}$=f(T_j); I_D=20 A; V_{GS}=10 V



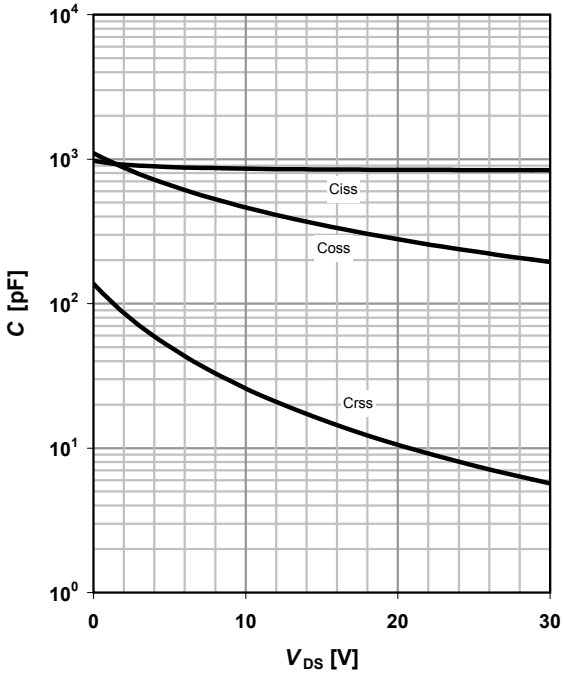
10 Typ. gate threshold voltage

$V_{GS(th)}$=f(T_j); V_{GS}=V_{DS}; I_D=250 µA



11 Typ. capacitances

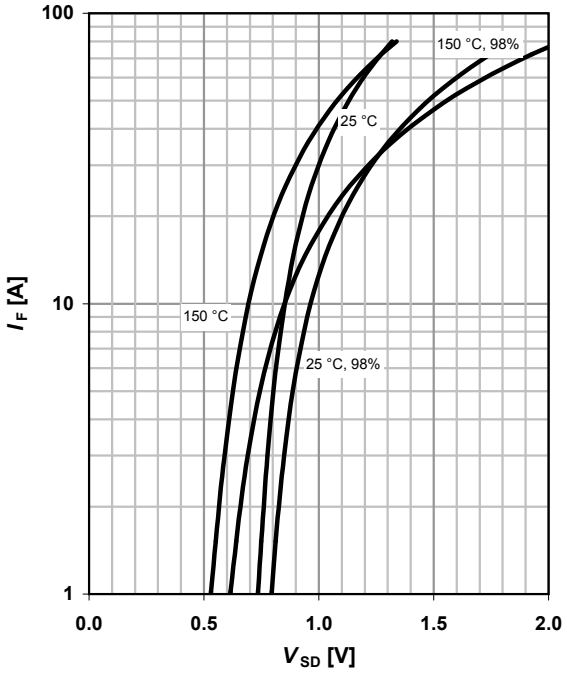
C=f(V_{DS}); V_{GS}=0 V; f=1 MHz



12 Forward characteristics of reverse diode

I_F=f(V_{SD})

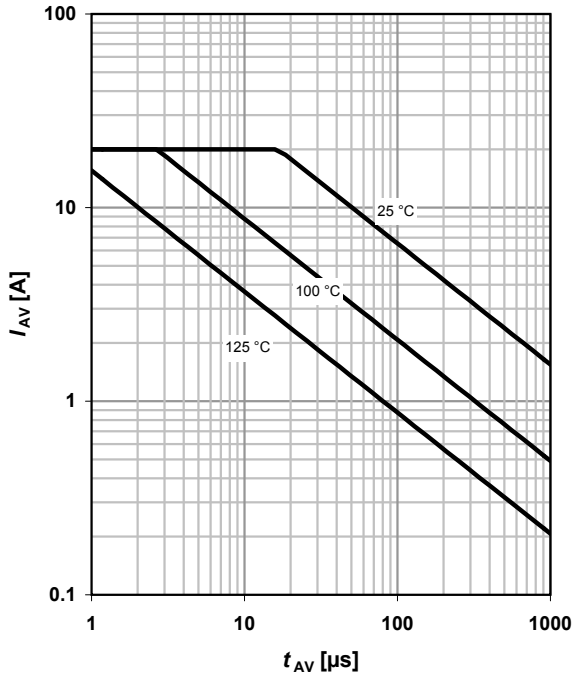
parameter: T_j



13 Avalanche characteristics

I_{AS}=f(t_{AV}); R_{GS}=25 Ω

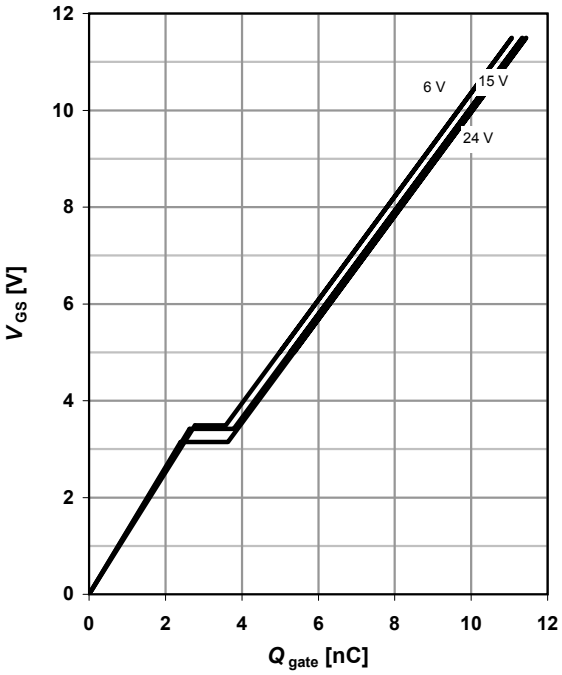
parameter: $T_{j(start)}$



14 Typ. gate charge

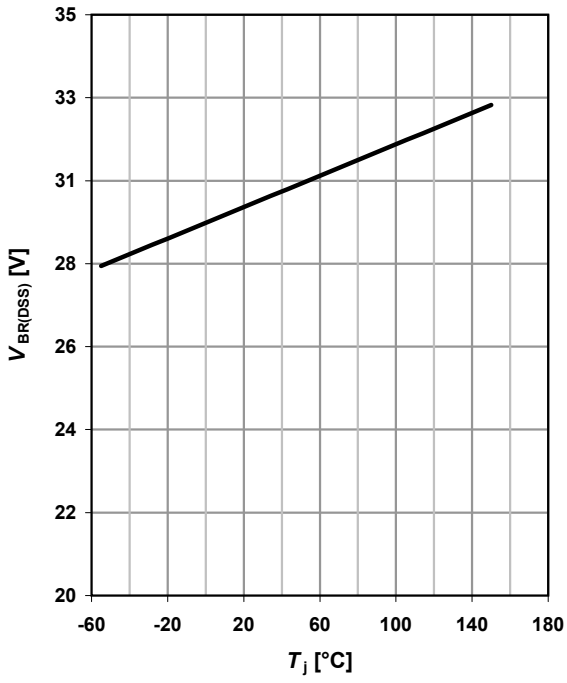
V_{GS}=f(Q_{gate}); I_D=20 A pulsed

parameter: V_{DD}

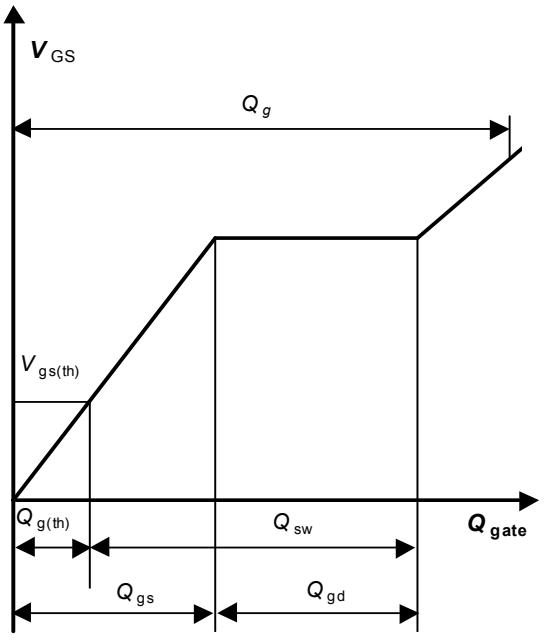


15 Drain-source breakdown voltage

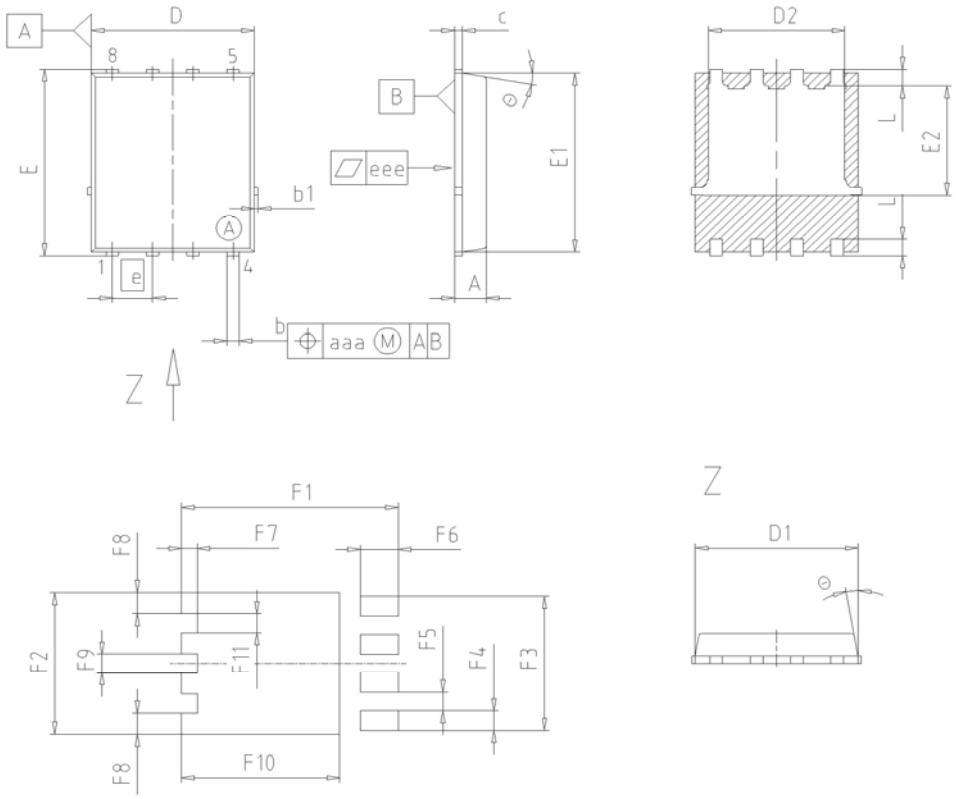
$V_{BR(DSS)}$=f(T_j); I_D=1 mA



16 Gate charge waveforms



Package Outline and Footprint **PG-TDSON-8 dual**

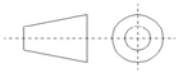


DIM	MILLIMETERS		INCHES	
	MIN	MAX	MIN	MAX
A	0.90	1.10	0.035	0.043
b	0.34	0.54	0.013	0.021
b1	0.02	0.22	0.001	0.008
c	0.15	0.35	0.006	0.014
D=D1	4.95	5.35	0.195	0.211
D2	4.20	4.40	0.165	0.173
E	5.95	6.35	0.234	0.250
E1	5.70	6.10	0.224	0.240
E2	3.40	3.80	0.134	0.150
e	1.27		0.050	
N	8		8	
L	0.45	0.65	0.018	0.026
□	8.5°	11.5°	8.5°	11.5°
aaa	0.25		0.010	
eee	0.05		0.002	
F1	6.75	6.95	0.266	0.274
F2	4.60	4.80	0.181	0.189
F3	4.36	4.56	0.172	0.180
F4	0.55	0.75	0.022	0.030
F5	0.52	0.72	0.020	0.028
F6	1.10	1.30	0.043	0.051
F7	0.40	0.60	0.016	0.024
F8	0.60	0.80	0.024	0.031
F9	0.53	0.73	0.021	0.029
F10	4.90	5.10	0.193	0.201
F11	0.53	0.73	0.021	0.029

DOCUMENT NO.
Z8B00003332

SCALE
0 2.5
0 2.5 5mm

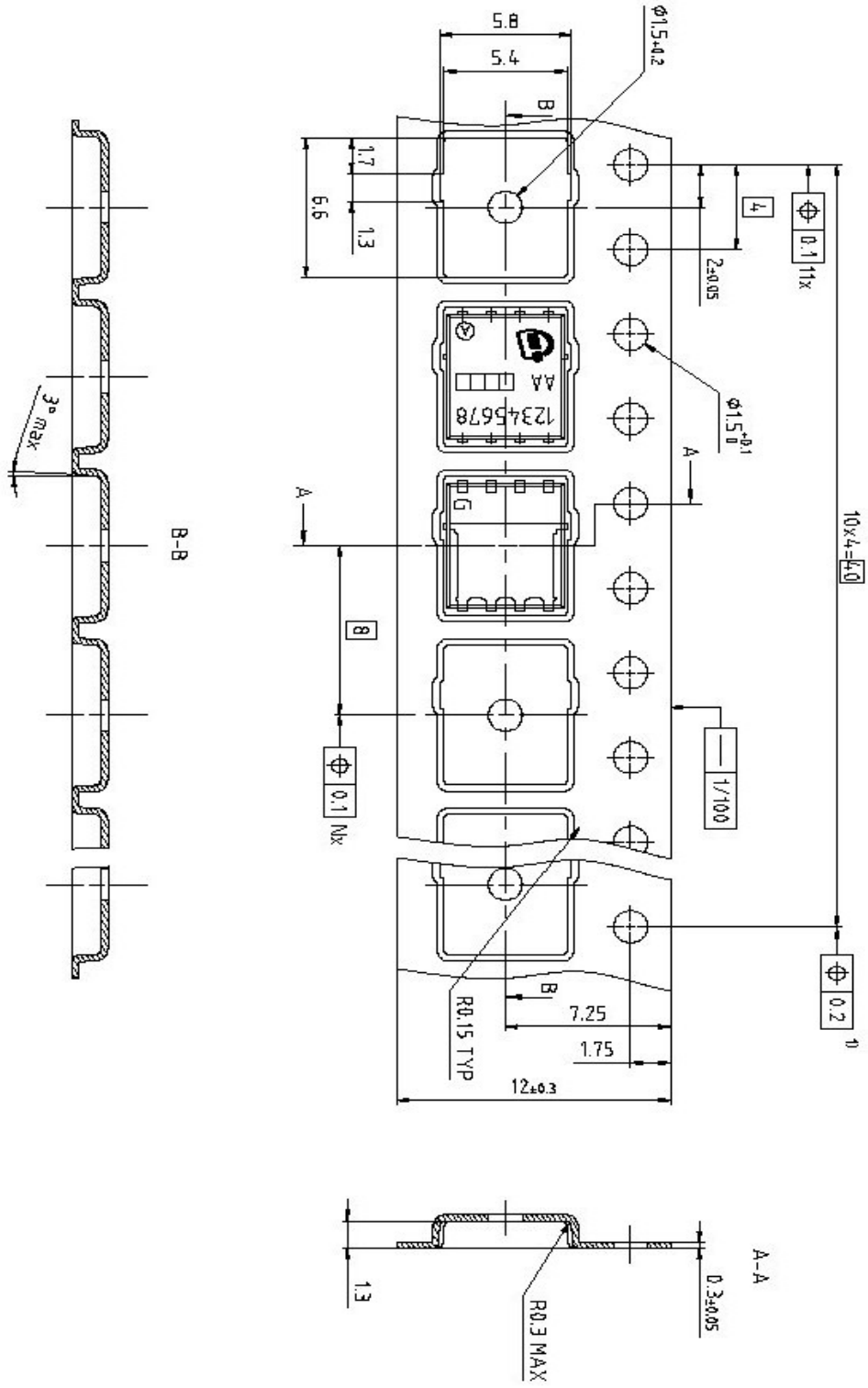
EUROPEAN PROJECTION



ISSUE DATE
08-03-2007

REVISION
03

Tape **PG-TDSON-8**



Dimensions in mm

Published by
Infineon Technologies AG
81726 Munich, Germany

Legal Disclaimer
The information given in this document shall in no event be regarded as a guarantee of conditions or characteristics. With respect to any examples or hints given herein, any typical values stated herein and/or any information regarding the application of the device, Infineon Technologies hereby disclaims any and all warranties and liabilities of any kind, including without limitation, warranties of non-infringement of intellectual property rights of any third party.

Information
For further information on technology, delivery terms and conditions and prices, please contact the nearest Infineon Technologies Office (www.infineon.com).

Warnings
Due to technical requirements, components may contain dangerous substances. For information on the types in question, please contact the nearest Infineon Technologies Office.
Infineon Technologies components may be used in life-support devices or systems only with the express written approval of Infineon Technologies, if a failure of such components can reasonably be expected to cause the failure of that life-support device or system or to affect the safety or effectiveness of that device or system. Life support devices or systems are intended to be implanted in the human body or to support and/or maintain and sustain and/or protect human life. If they fail, it is reasonable to assume that the health of the user or other persons may be endangered.